

FIG. 1 (Prior Art)

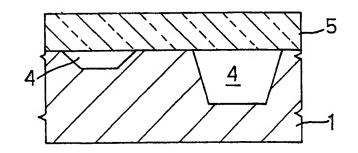


FIG. 2 (Prior Art)

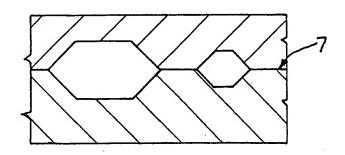


FIG. 3 (Prior Art)

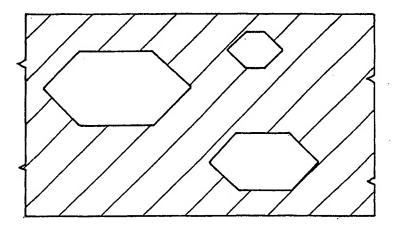


FIG. 4

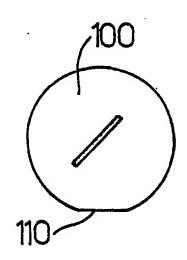


FIG. 5

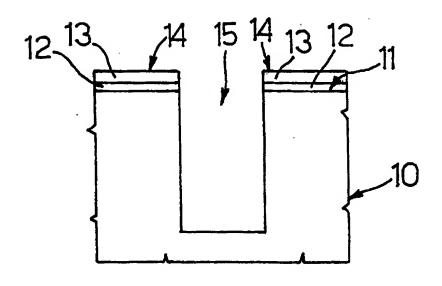
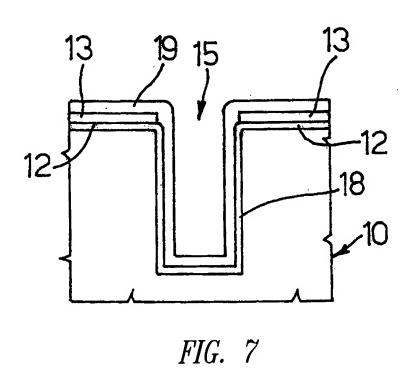


FIG. 6



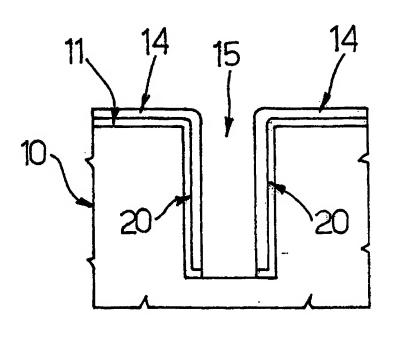


FIG. 8

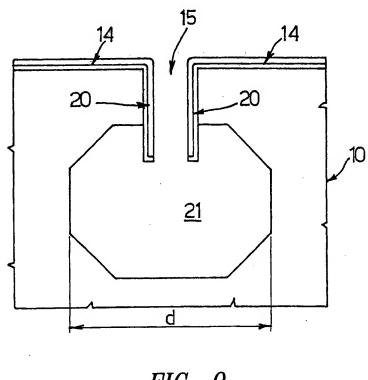


FIG. 9

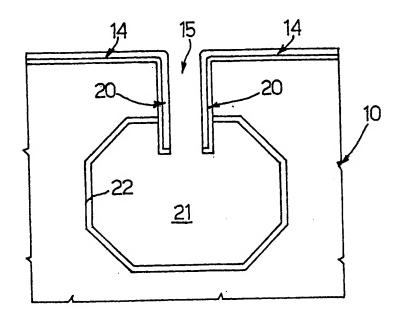


FIG. 10

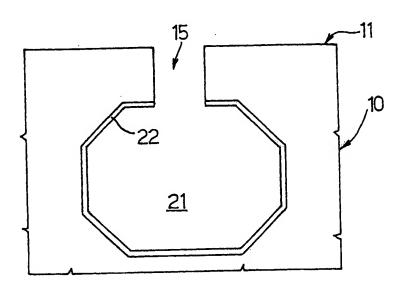


FIG. 11

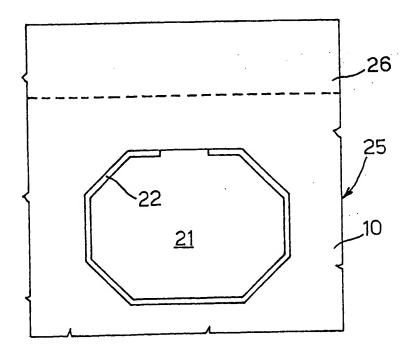
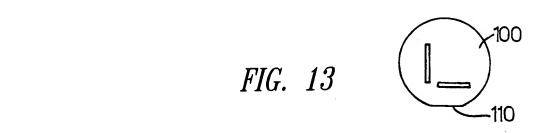
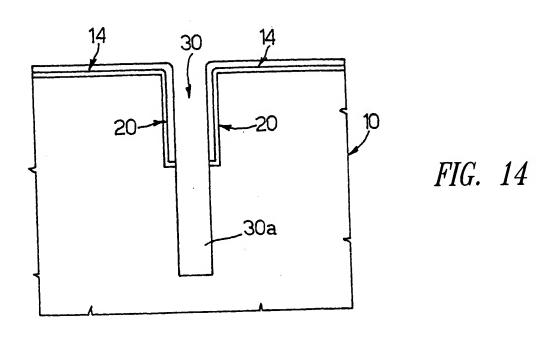
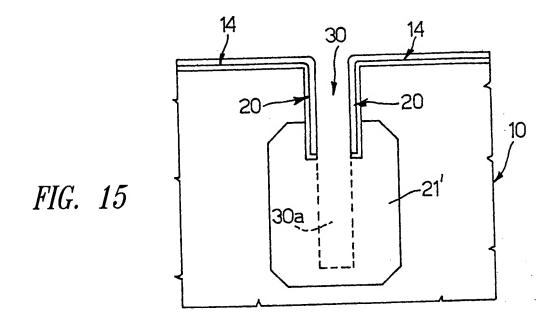
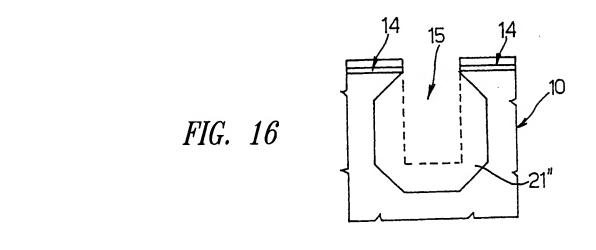


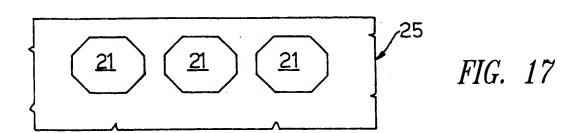
FIG. 12

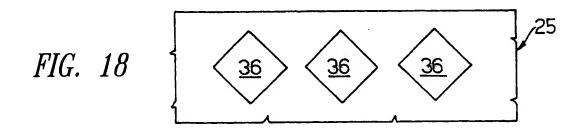


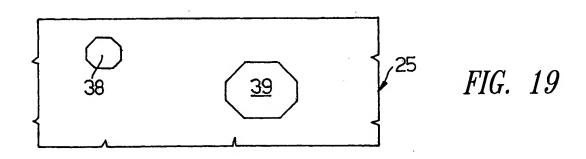






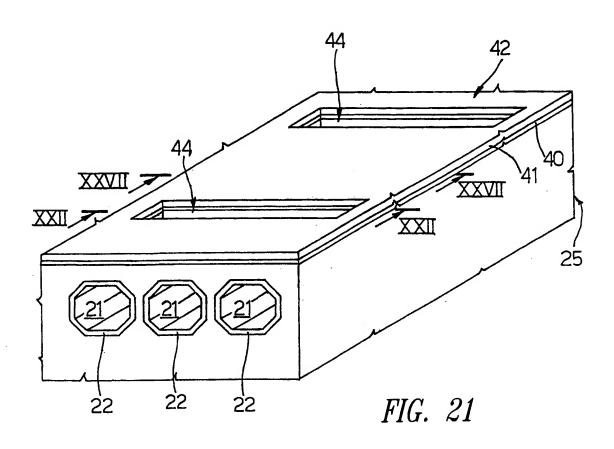






Inventor(s): Gabriele Barlocchi et al. Express Mail No. EV336596659US Docket No. 854063.552D1

d FIG. 20



Title: METHOD FOR FORMING HORIZONTAL BURIED CHANNELS OR CAVITIES IN WAFERS OF

MONOCRYSTALLINE SEMICONDUCTOR MATERIAL

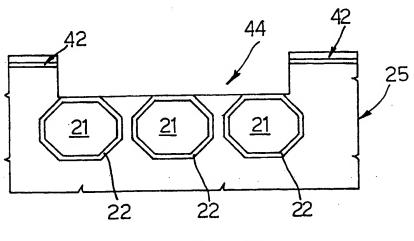


FIG. 22

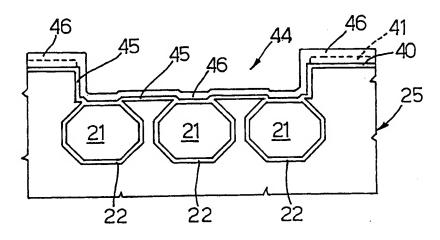
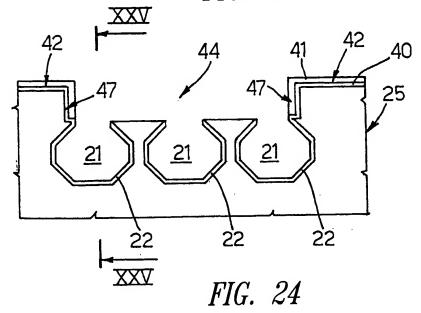


FIG. 23



Title: METHOD FOR FORMING HORIZONTAL BURIED CHANNELS OR CAVITIES IN WAFERS OF

MONOCRYSTALLINE SEMICONDUCTOR MATERIAL

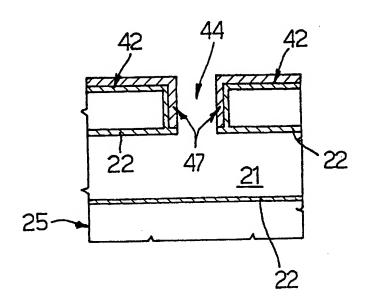


FIG. 25

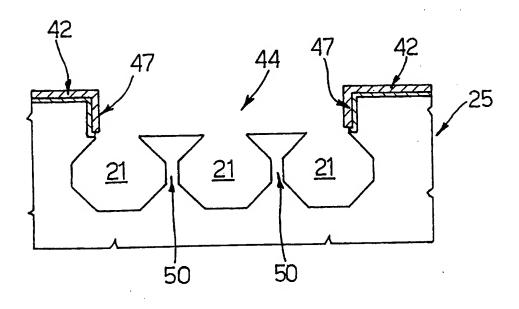


FIG. 26

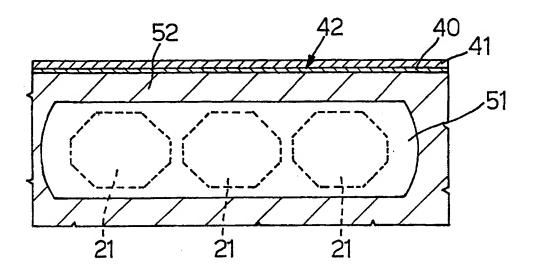


FIG. 27

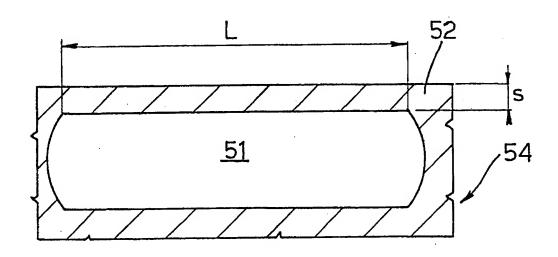


FIG. 28